



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

1.MATERIAL:

HOUSING: PBT, BLACK, UL94V-0  
 CONTACTS: 0.35[0.014] THICK PHOSPHOR BRONZE PLATED WITH  
 100μ" MINIMUM THICK TIN IN SOLDER AREA.  
 15μ" MINIMUM GOLD IN LOCALIZED PLATE AREA.  
 ENTIRE CONTACTS PLATED WITH 30μ" MINIMUM THICK NICKEL.

2.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

3.PART NUMBER: HRJ800615-U1688-F2

		UNIT	SCALE	SHEET	TITLE:
		mm[inch]		1 of 1	RJ45, MODULAR JACK, 1X6, W/O LED, 8P, 8C, UNSHIELDED, THRU-HOLE
		DRAWN BY 董正一		APPROVED BY 董正一	
		2004.08.23		2004.08.23	
GENERAL TOLERANCE					
B1	REVISE	2005.12.30	X.X±0.25	ANGLE±	DRAW NO. : HRJ800615-U1688-F2
B0	NEW RELEASE	2005.12.22	X.XX±0.15		
REV.	DESCRIPTION	DATE	X.XXX±0.05		
					REV. B1